



**PATENT APPLICATION**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re application of

Docket No: Q62230

Takayuki YAMAMOTO , et al.

Appln. No.: 09/735,892

Group Art Unit: 1771

Confirmation No.: 5759

Examiner: Daniel R. Zirker

Filed: December 14, 2000

For: REMOVABLE PRESSURE-SENSITIVE ADHESIVE SHEET

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**AMENDMENT UNDER 37 C.F.R. § 1.111**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

This Amendment is submitted in response to the Office Action dated March 20, 2003. A petition for one-month extension of time is being concurrently filed, making a response due on or before July 20, 2003. Please amend the above-identified application as follows:

**IN THE CLAIMS:**

**Please enter the following amended claims:**

5. (Twice Amended) A semiconductor wafer processing method, comprising adhering a removable pressure-sensitive adhesive sheet which comprises a pressure-sensitive adhesive layer which is made of at least a pressure-sensitive adhesive comprising a polymer in which the content of low-molecular components having a molecular weight of  $10^5$  or lower is 10% by weight or lower, and the polymer has a weight average molecular weight of 930,000 to 2,100,000, to a front or back surface of the wafer, and processing the wafer.